

Features & Benefits

- Full cure at room temperature
- Adhesion to a variety of substrates
- Thermally conductive
- High temperature resistance
- Excellent chemical resistance

Description

PERMABOND® ET5441 is a thermally conductive two-component adhesive based on epoxy resin. It is specifically designed to bond metal substrates when excellent resistance to high temperature is required. The full cure is achieved in 7 days at room temperature, but it can be obtained in 24 hours at room temperature followed by 30 minutes at +80°C (176°F). Permabond ET5441 provides excellent resistance to motor oil, glycol and hot and cold water.

Physical Properties of Uncured Adhesive

	ET5441A	ET5441B
Chemical composition	Epoxy Resin	Amine Hardener
Appearance	White	Dark Grey
Viscosity @ 23°C	20,000-30,000 mPa.s (cP)	17,000-23,000 mPa.s (cP)
Specific gravity	2.1	2.1

Typical Curing Properties

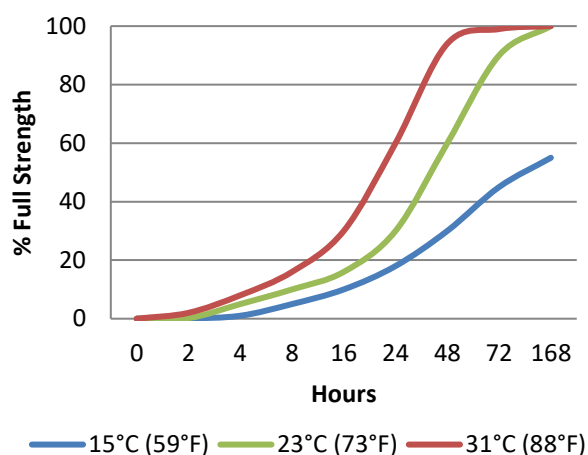
Mix ratio	2:1 by weight 2:1 by volume
Usable / pot life @25°C (77°F)	150 minutes
Working strength @25°C (77°F)	8 hours
Full cure @25°C (77°F)	7 days

Typical Performance of Cured Adhesive

Shear strength* (ISO4587)	Steel: 20 N/mm² (2900 psi) Aluminium: 15 N/mm² (2200 psi) ABS: 6 N/mm² (880 psi)
Tensile strength at break (DIN 53504)	50 N/mm² (7250 psi)
Elongation at Break	2.9%
Tg (DSC)	65°C (149°F)
Tg (DSC) 24h@ 25°C + 30min @80°C	113°C (235°F)
Thermal Conductivity (ISO 8302)	1.1 W/(m.K)

*Strength results will vary depending on the level of surface preparation and gap.

Strength Development



Graph shows typical strength development of bonded components. An increase of 8°C (46°F) in temperature will halve the cure time. Lower temperatures will result in a slower cure time.

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Hot Strength

Test Temperature	Curing Conditions		
	7 days 23°C (73°F)	24h 23°C (73°F) + 1h 60°C (140°F)	2h 80°C (176°F)
23°C (73°F)	100%	100%	100%
80°C (176°F)	117%	126%	108%
150°C (302°F)	41%	44%	43%
200°C (392°F)	30%	30%	31%

"Hot strength" shear strength tests performed on mild steel. Fully cured specimens conditioned to pull temperature for 30 minutes before testing at temperature. Results show % strength retained compared with room temperature control.

ET5441 can withstand higher temperatures for brief periods (such as for paint baking and wave soldering processes) providing the joint is not unduly stressed. The minimum temperature the cured adhesive can be exposed to is -40°C (-40°F) depending on the materials being bonded.

Additional Information

This product is not recommended for use in contact with strong oxidizing materials.

Information regarding the safe handling of this material may be obtained from the safety data sheet (SDS).

Users are reminded that all materials, whether innocuous or not, should be handled in accordance with the principles of good industrial hygiene.

This Technical Datasheet (TDS) offers guideline information and does not constitute a specification.

Storage & Handling

Storage Temperature	5 to 25°C (41 to 77°F)
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Surface Preparation

Surfaces should be clean, dry and grease-free before applying the adhesive. Use a suitable solvent (such as acetone or isopropanol) for the degreasing of surfaces. Some metals such as aluminium, copper and its alloys will benefit from light abrasion with emery cloth (or similar), to remove the oxide layer.

Directions for Use

- Dual cartridges:
 - Insert the cartridge into the application gun and guide the plunger into the cartridge.
 - Remove the cartridge cap and dispense material until both sides are flowing.
 - Attach the static mixer to the end of the cartridge and begin dispensing the material.
- Apply material to one of the substrates.
- Join the parts. Parts must be joined within 2 hours of mixing the two epoxy components.
- Large quantities and/or higher temperature will decrease the usable life or pot life.
- Apply pressure to the assembly by clamping for at least 4 hours until handling strength is obtained.
- Full cure will be obtained after 7 days at 23°C (73°F). Heat can be used to accelerate the curing process.

NB. Exercise caution when mixing large quantities due to exothermic reaction.

Video Links

Surface preparation:

<https://youtu.be/8CMOMP7hXjU>

Two-part epoxy directions for use:

<https://youtu.be/GRX1RyknYqc>



Supplied by:
www.hitek-ltd.co.uk
 +44 (0)1724 851678



HITEK
 ELECTRONIC MATERIALS LTD

www.permabond.com

• UK: 0800 975 9800

• General Enquiries: +44 (0)1962 711661

• US: 732-868-1372

• Asia: + 86 21 5773 4913

info.europe@permabond.com

info.americas@permabond.com

info.asia@permabond.com

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